

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)	Q _g (Typ.)	
30	0.099 at $V_{GS} = 4.5 \text{ V}$	1.2 ^a	3.5	
	0.140 at V _{GS} = 2.5 V	1.0	3.5	

FEATURES

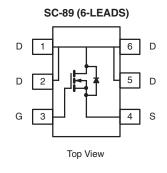
- Halogen-free Option Available
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested

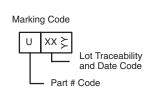


RoHS

APPLICATIONS

· Load Switch for Portable Devices





Ordering Information: Si1070X-T1-E3 (Lead (Pb)-free) Si1070X-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise no	ted	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 12	v
Continuous Drain Current /T 150 °C\a	T _A = 25 °C	I_	1.2 ^{b, c}	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	l _D	1 ^{b, c}	A
Pulsed Drain Current		I _{DM}	6	^
Avalanche Current	L = 0.1 mH	I _{AS}	9	
Repetitive Avalanche Energy	L = 0.111111	E _{AS}	4.01	mJ
ontinuous Source-Drain Diode Current T _A = 25 °C		I _S	0.2 ^{b, c}	A
Maniana Dania Diazinatian	T _A = 25 °C	P _D	0.236 ^{b, c}	w
Maximum Power Dissipation ^a	T _A = 70 °C	' Б	0.151 ^{b, c}	• • • • • • • • • • • • • • • • • • • •
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Manifestor Longition to Aughtinoph d	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum Junction-to-Ambient ^{b, d}	Steady State		540	650	C/VV	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under Steady State conditions is 650 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		24.5		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 230 μA		- 3.81		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.7		1.55	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	nA
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	6			Α
Drain-Source On-State Resistance ^a	R	$V_{GS} = 4.5 \text{ V}, I_D = 1.2 \text{ A}$		0.082	0.099	Ω
	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 1.0 \text{ A}$		0.116	0.140	
Forward Transconductance	9 _{fs}	V _{DS} = 15 V, I _D = 1.2 A		5		S
Dynamic ^b						
Input Capacitance	C _{iss}			385		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		55		
Reverse Transfer Capacitance	C _{rss}			30		
Tatal Oata Obarra		$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 1.2 \text{ A}$		3.8	8.3	
Total Gate Charge	Q_g			3.5	4.1	nC
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 4.6 \text{ A}$		1.1		
Gate-Drain Charge	Q_{gd}			0.98		
Gate Resistance	R _g	f = 1 MHz		4.7	6.2	Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 15 \Omega$		22	33	ns
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 1.0 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		14	21	
Fall Time	t _f	-		6	9	
Drain-Source Body Diode Characterist	ics		•			
Pulse Diode Forward Current ^a	I _{SM}				6	Α
Body Diode Voltage	V _{SD}	I _S = 1.2 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			19.4	29.5	nC
Body Diode Reverse Recovery Charge	Q_{rr}	1 2 2 A d1/d+ 100 A/:		18.43	27.5	
Reverse Recovery Fall Time	t _a	I _F = 3.8 A, dl/dt = 100 A/μs		16.4		ns
Reverse Recovery Rise Time	t _b			3		

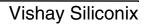
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

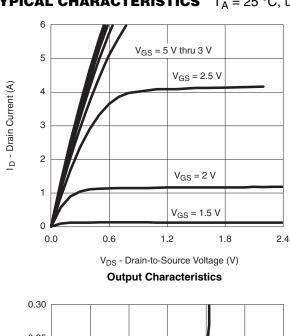
b. Guaranteed by design, not subject to production testing.

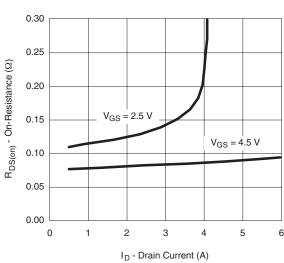


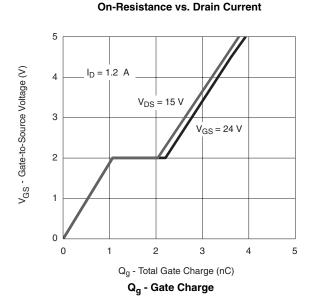


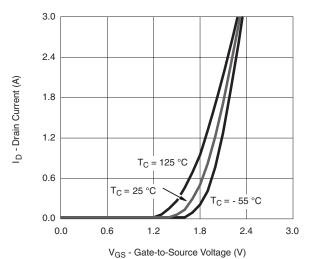


TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

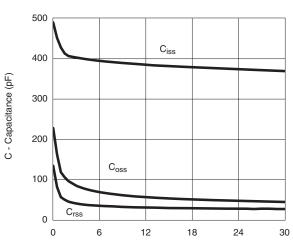




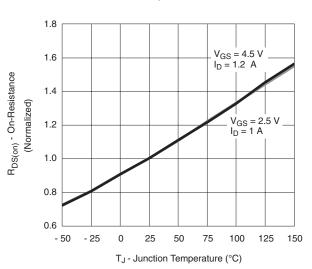








 V_{DS} - Drain-to-Source Voltage (V) $\label{eq:capacitance}$

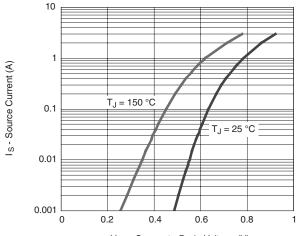


On-Resistance vs. Junction Temperature

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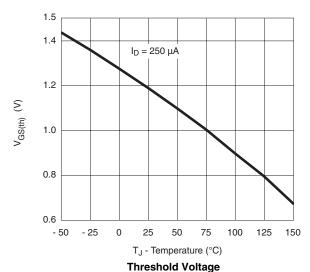
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TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



V_{SD} - Source-to-Drain Voltage (V)

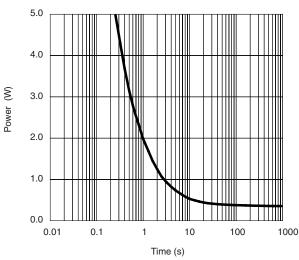
Source-Drain Diode Forward Voltage



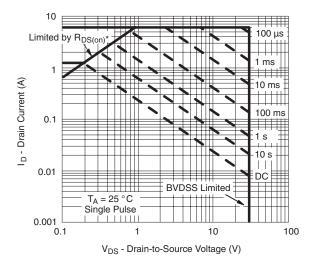
0.24 $T_{A} = 125 \, ^{\circ}\text{C}$ 0.00

0 1 2 3 4 5 V_{GS} - Gate-to-Source Voltage (V)

 $R_{DS(on)}$ vs. V_{GS} vs. Temperature



Single Pulse Power

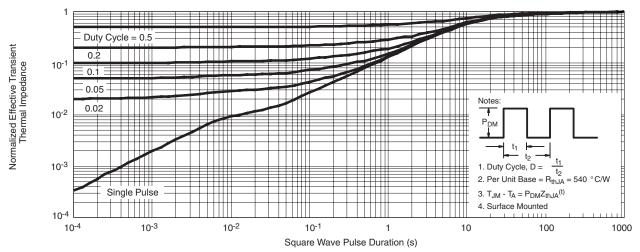


* $V_{GS} > \mbox{ minimum } V_{GS}$ at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

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